ESP-WROOM-02

Datasheet

Note:

It is recommended to use the upgraded model: <u>ESP8684-WROOM-02C</u>



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About This Guide

This document provides introduction to the specifications of ESP-WROOM-02 hardware.

Release Notes

Date	Version	Release notes
2015.12	V0.5	First release.
2016.01	V0.6	Updated Section 3.2.2.
2016.02	V0.7	Added Appendix—Notices.Updated Chapter 1.
2016.04	V0.8	Updated the flash size and PAD (bottom) size.
2016.06	V0.9	Updated the flash size.
2016.06	V1.0	 Added Appendix—Notices—B.5. Updated Figure 2-1.
2016.08	V1.1	Updated the operating temperature range.
2016.11	V1.2	 Added Appendix—Learning Resources. Added "ESP-WROOM-02 Peripheral Schematics" in Chapter 5.
2016.11	V2.0	 Added Section 4.8 "Electrostatic Discharge". Updated Figure 5-1. ESP-WROOM-02 Schematics.
2016.12	V2.1	 Changed the minimum working voltage from 3.0 V to 2.5 V. Changed the power consumption during Deep-sleep from 10 μA to 20 μA.
2017.02	V2.2	Updated Section 3.3.
2017.04	V2.3	 Added the module's dimensional tolerance; Changed the input impedance value in Table 4-4 and 4-5 from 50 Ω to 39 + j6 Ω; Added Figure 4-1 Reflow Profile.

Date	Version	Release notes
2017.09	V2.4	 Added Documentation Change Notification and the official link for downloading Product Certificates; Updated the supply voltage to 2.7 V ~ 3.6 V; Updated Figure 2-1 ESP-WROOM-02 Pin Layout and added a note to it; Updated Chapter 4: Collated electrical-characteristics-related data into Table 4-1; collated Wi-Fi-radio-related data into Table 4-2 and updated the output power parameters; Updated Chapter 5 Schematics and added a note; Added Chapter 6 Dimensions. Deleted Appendix B—Notices.
2017.10	V2.5	Updated the note to ESP-WROOM-02 Peripheral Schematics in Chapter 5.
2018.03	V2.6	 Deleted the note in Chapter 1; Deleted the "RF certification" column and added a new "Certificates" section with all acquired certifications listed in Table 1-1; Updated Section 3.1 and Section 3.2; Updated Figure 4-1.
2018.04	V2.7	Deleted the "Bluetooth certification" part in Table 1-1.
2018.06	V2.8	Updated Figure 1-1 and Figure 6-1;Updated Chapter 1 for module size.
2018.08	V2.9	 Updated Chapter 1 for module size, and add information of reliability test items; Updated Figure 6-1 Dimensions of ESP-WROOM-02; Added Chapter 7 Recommended PCB Land Pattern; Updated the cover page.
2019.08	V3.0	Updated Chapter 6 Peripheral Schematics.
2019.12	V3.1	Added a note for the reflow profile;Added feedback links.
2020.07	V3.2	Updated Note in Chapter 6;Updated links in Appendix.
2021.08	V3.3	Added the "Not Recommended For New Designs (NRND)" watermark and footers.
2022.03	V3.4	Added a link to RF certification in Table 1-1
2023.06	v3.5	Added a note on the cover page;Updated two documents in Appendix.
2023.09	v3.6	Updated Figure 6-1 and Figure 7-1.

Documentation Change Notification

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Certification

Download certificates for Espressif products from <u>https://www.espressif.com/en/</u> certificates.

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1.

Overview

Espressif provides the SMD module—ESP-WROOM-O2 that integrates ESP8266EX. The module has been adjusted to get the best RF performance. We recommend using ESP-WROOM-O2 for tests or for further development.

Wote:

For more information on ESP8266EX, please refer to ESP8266EX Datasheet.

The module size is (18.00 \pm 0.20) mm x (20.00 \pm 0.20) mm x (2.80 \pm 0.15) mm. The type of flash used on this module is an SPI flash with a package size of SOP 8-150 mil. The gain of the on-board PCB antenna is 2 dBi.



Figure 1-1. ESP-WROOM-02 Module



Categories	Items	Specifications
	RF certification	See certificates for ESP-WROOM-02
Certification	Wi-Fi certifaction	Wi-Fi Alliance
	Green certification	RoHS, REACH
Test	Reliablity	HTOL/HTSL/uHAST/TCT/ESD
Wi-Fi	Wi-Fi protocols	802.11 b/g/n
	Frequency range	2.4 GHz ~ 2.5 GHz (2400 MHz ~ 2483.5 MHz)
	Peripheral interface	UART/HSPI/I2C/I2S/IR Remote Control
	Penpheral Interface	GPIO/PWM
	Operating voltage	2.7 V ~ 3.6 V
	Operating current	Average: 80 mA
Hardware	Minimum current delivered by power supply	500 mA
	Operating temperature range	−40 °C ~ 85 °C
	Storage temperature	−40 °C ~ 85 °C
	Package size	(18.00 ± 0.20) mm x (20.00 ± 0.20) mm x (2.80±0.15) mm
	External interface	-
	Wi-Fi mode	Station/SoftAP/SoftAP + Station
	Security	WPA/WPA2
	Encryption	WEP/TKIP/AES
Software	Firmware upgrade	UART Download/OTA (via network)/Download and write firmware via host
	Software development	Supports Cloud Server Development/SDK for custom firmware development
	Network protocols	IPv4, TCP/UDP/HTTP/FTP
	User configuration	AT Instruction Set, Cloud Server, Android/iOS app

Table 1-1. ESP-WROOM-02 Specifications



Pin Description

Figure 2-1 shows the pin distribution of the ESP-WROOM-02.





ESP-WROOM-02 has 18 pins. Please see the pin definitions in Table 2-1.

Table 2-1.	ESP-WROOM-02	Pin	Definitions

No.	Pin Name	Functional Description
		3.3 V power supply (VDD)
1	3V3	III Note:
'	505	It is recommended the maximum output current a power supply provides be of 500 mA or above.
2	EN	Chip enable pin. Active high.
3	IO14	GPIO14; HSPI_CLK
4	1012	GPIO12; HSPI_MISO
5	IO13	GPI013; HSPI_MOSI; UARTO_CTS



No.	Pin Name	Functional Description
6	1015	GPI015; MTDO; HSPICS; UARTO_RTS Pull down.
7	102	GPIO2; UART1_TXD Floating (internal pull-up) or pull up.
8	100	GPIOOUART download: pull down.Flash boot: floating or pull up.
9	GND	GND
10	104	GPI04
11	RXD	UARTO_RXD, receive end in UART download; GPIO3
12	TXD	UARTO_TXD, transmit end in UART download, floating or pull up; GPI01
13	GND	GND
14	105	GPI05
15	RST	Reset
16	TOUT	It can be used to test the power-supply voltage of VDD3P3 (Pin3 and Pin4) and the input power voltage of TOUT (Pin6). These two functions cannot be used simultaneously.
17	1016	GPI016; used for Deep-sleep wake-up when connected to RST pin.
18	GND	GND



Functional Description

MCU 3.1.

ESP8266EX integrates a Tensilica L106 32-bit RISC processor, which achieves extra-low power consumption and reaches a maximum clock speed of 160 MHz. The Real-Time Operating System (RTOS) and Wi-Fi stack allow 80% of the processing power to be available for user application programming and development. The CPU includes the interfaces as below.

- Programmable RAM/ROM interfaces (iBus), which can be connected with memory controller, and can also be used to visit flash.
- · Data RAM interface (dBus), which can connected with memory controller.
- AHB interface which can be used to visit the register.

3.2. Memory

3.2.1. Internal SRAM and ROM

ESP8266EX Wi-Fi SoC integrates memory controller and memory units including SRAM and ROM. MCU can access the memory units through iBus, dBus, and AHB interfaces. All memory units can be accessed upon request, while a memory arbiter will decide the running sequence according to the time when these requests are received by the processor.

According to our current version of SDK, SRAM space available to users is assigned as below.

- RAM size < 50 kB, that is, when ESP8266EX is working under the Station mode and connects to the router, programmable space accessible in heap + data section is around 50 kB.
- There is no programmable ROM in the SoC, therefore, user program must be stored in an external SPI flash.

3.2.2. SPI Flash

ESP8266EX uses external SPI flash to store user programs, and supports up to 16 MB memory capacity theoretically.



ESP-WROOM-02 currently integrates a 2-MB SPI flash. ESP-WROOM-02 supports these SPI modes: Standard SPI, DIO (Dual I/O), DOUT (Dual Output), QIO (Quad I/O) and QOUT (Quad Output).

Crystal Oscillator 3.3.

ESP-WROOM-02 uses a 26-MHz crystal oscillator. The accuracy of the crystal oscillator should be ± 10 PPM.

When using the download tool, please select the right type of crystal oscillator. In circuit design, capacitors C1 and C2 which connect to the earth are added to the input and output terminals of the crystal oscillator respectively. The values of the two capacitors can be flexible, ranging from 6 pF to 22 pF, however, the specific capacitive values depend on further testing of, and adjustment to, the overall performance of the whole circuit. Normally, the capacitive values of C1 and C2 are within 10 pF for the 26-MHz crystal oscillator.

Table 3-1. Interface Description

Interface	Pin	Functional Description
HSPI	IO12 (MISO), IO13 (MOSI), IO14 (CLK), IO15 (CS)	Connects to SPI Flash, display screen, and MCU.
PWM	IO12 (R), IO15 (G), IO13 (B)	Currently the PWM interface has four channels, but users can extend it to eight channels. PWM interface can realize the control of LED lights, buzzers, relays, electronic machines, etc.
IR	1014 (IR_T), 105 (IR_R)	The functionality of the infrared remote control interface can be realized via software programming. The interface uses NEC coding, modulation, and demodulation. The frequency of the modulated carrier signal is 38 kHz.
ADC	тоит	Tests the power supply voltage of VDD3P3 (Pin3 and Pin4) and the input power voltage of TOUT (Pin6). However, these two functions cannot be used simultaneously. This interface is typically used in sensors.
12C	1014 (SCL), 102 (SDA)	Connects to external sensors and display screens, etc.

Interface Description 3.4.

2024.01

2024.01



Interface	Pin	Functional Description		
UART	UARTO: TXD (UOTXD), RXD (UORXD), IO15	Communicates with the UART device. Downloading: UOTXD + UORXD or GPIO2 + UORXD Communicating: (UARTO): UOTXD, UORXD, MTDO (UORTS), MTCK (UOCTS) Debugging: UART1_TXD (GPIO2) can be used to print debugging information.		
	(RTS), IO13 (CTS) UART1: IO2 (TXD)	By default, UARTO will output some printed information when you power on ESP8266EX. If this issue influences some specific applications, users can exchange the inner pins of UART when initializing ESP8266EX, that is, exchange UOTXD and UORXD with UORTS and UOCTS. Users can connect MTDO and MTCK to the serial port of the external MCU to realize the communication.		
125	I2S input: IO12 (I2SI_DATA) ; IO13 (I2SI_BCK); IO14 (I2SI_WS);	Collects, processes and transmits audio data.		
125	I2S output: I015 (I2SO_BCK); I03 (I2SO_DATA); I02 (I2SO_WS).	_ ` `		



Electrical Characteristics

Dote:

Unless otherwise specified, measurements are based on VDD = 3.3 V, TA = 25 °C.

4.1. Electrical Characteristics

Parameter	Symbol	Min	Тур	Max	Unit
Storage temperatue	-	-40	Normal	85	°C
Operating temperature	-	-40	20	85	°C
Maximum soldering temperature (Condition: IPC/JEDEC J-STD-020)	-	-	-	260	°C
Supply voltage	VDD	2.7	3.3	3.6	V
Input logic level low	V _{IL}	-0.3	-	0.25 VDD	V
Input logic level high	V _{IH}	0.75 VDD	-	VDD + 0.3	V
Output logic level low	V _{OL}	-	-	0.1 VDD	V
Output logic level high	V _{OH}	0.8 VDD	-	-	V

Table 4-1. Electrical Characteristics

4.2. Wi-Fi Radio

Table 4-2. Wi-Fi Radio Characteristics

Description	Min	Тур	Max	Unit	
Input frequency	2412	-	2484	MHz	
Input reflection	-	-	-10	dB	
	Output Po	wer			
PA output power at 72.2 Mbps	13	14	15	dBm	
PA output power in 11b mode	19.5	20	20.5	dBm	
Sensitivity					



Description	Min	Тур	Max	Unit
DSSS, 1 Mbps	-	-98	-	dBm
CCK, 11 Mbps	-	-91	-	dBm
6 Mbps (1/2 BPSK)	-	-93	-	dBm
54 Mbps (3/4 64-QAM)	-	-75	-	dBm
HT20, MCS7 (65 Mbps, 72.2 Mbps)	-	-72	-	dBm
	Adjacent channe	el rejection		
OFDM, 6 Mbps	-	37	-	dB
OFDM, 54 Mbps	-	21	-	dB
HT20, MCS0	-	37	-	dB
HT20, MCS7	-	20	-	dB

4.3. Power Consumption

The following power consumption data were obtained from the tests with a 3.3 V power supply and a voltage stabilizer, in 25 °C ambient temperature. All data are based on 50% duty cycle in continuous transmission mode.

Table 4-3.	Power	Consumption
------------	-------	-------------

Modes	Min	Тур	Max	Unit
Tx 802.11 b, CCK 11 Mbps, Pout = +17 dBm	-	170	-	mA
Tx 802.11 g, OFDM 54 Mbps, Pout = +15 dBm	-	140	-	mA
Tx 802.11 n, MCS7, Pout = +13 dBm	-	120	-	mA
Rx 802.11 b, 1024 bytes packet length, -80 dBm	-	50	-	mA
Rx 802.11 g, 1024 bytes packet length, -70 dBm	-	56	-	mA
Rx 802.11 n, 1024 bytes packet length, -65 dBm	-	56	-	mA
Modem-sleep	-	15	-	mA
Light-sleep2	-	0.9	-	mA
Deep-sleep③	-	20	-	μΑ
Power Off	-	0.5	-	μΑ



Dotes:

- ① Modem-sleep is used when such applications as PWM or I2S require the CPU to be working. In cases where Wi-Fi connectivity is maintained and data transmission is not required, the Wi-Fi Modem circuit can be shut down to save power, according to 802.11 standards (such as U-APSD). For example, in DTIM3, when ESP8266EX sleeps for 300 ms and wakes up for 3 ms to receive Beacon packages from AP, the overall average current consumption is about 15 mA.
- ② Light-sleep is used for applications whose CPU may be suspended, such as Wi-Fi switch. In cases where Wi-Fi connectivity is maintained and data transmission is not required, Wi-Fi Modem circuit and CPU can be shut down to save power, according to 802.11 standards (such as U-APSD). For example, in DTIM3, when ESP8266EX sleeps for 300 ms and wakes up for 3 ms to receive Beacon packages from AP, the overall average current consumption is about 0.9 mA.
- ③ Deep-sleep is for applications that do not require Wi-Fi connectivity and only transmit data over long time lags, e.g., a temperature sensor that measures temperature every 100 s. For example, when ESP8266EX sleeps for 300 s then wakes up to connect to AP (taking about 0.3 ~ 1 s), the overall average current consumption is far less than 1 mA. The current consumption of 20 μA was obtained at the voltage of 2.5 V.

4.4. Reflow Profile





Figure 4-1. ESP-WROOM-02 Reflow Profile

Note:

Solder the module in a single reflow. If the PCBA requires multiple reflows, place the module on the PCB during the final reflow.

4.5. Electrostatic Discharge

Table 4-4. Electrostatic Discharge Parameters	
Symbol Reference	Level

Name	Symbol	Reference	Level	Max	Unit
Electrostatic Discharge	Vesd	Temperature: 23 ± 5 °C	2	2000	
(Human - Body Model)	(HBM)	Based on ANSI/ESDA/JEDEC JS - 001 - 2014	2	2000	
Electrostatic Discharge	Vesd	Temperature: 23 ± 5 °C			V
(Charged - Device Model)	(CDM)	Based on JEDEC EIA/JESD22 - C101F	C2	500	



Schematics







Peripheral Schematics



Figure 5-2. ESP-WROOM-02 Peripheral Schematics

Dote:

- 1. Soldering Pad 19 to the Ground of the base board is not necessary for a satisfactory thermal performance. If users do want to solder it, they need to ensure that the correct quantity of soldering paste is applied.
- To ensure the power supply to the ESP8266EX chip during the power-up, it is advised to add an RC delay circuit at the EN pin. The recommended setting for the RC delay circuit is usually R = 10 kΩ and C = 0.1 uF. However, specific parameters should be adjusted based on the power-up timing of the module and the power-up and reset timing of the ESP8266 chip. For ESP8266EX's Power-up and Reset Timing Diagram, please refer to Electrical Characteristics in ESP8266EX Datasheet.
- 3. To improve module's anti-inference capability, it is advised to reserve an RC delay circuit at the RST pin. The recommended setting for the RC delay circuit is usually $R=10 k\Omega$ and C=0.1 uF.



7.

Dimensions



Figure 6-1. Dimensions of ESP-WROOM-02



8.

Recommended PCB Land Pattern







Appendix—Learning Resources Δ_

A.1. **Must-Read Documents**

ESP-AT Instruction User Guide

Description: This document provides users with detailed information on what is ESP-AT, how to connect hardware, and how to download and flash AT firmware.

ESP8266 SDK Getting Started Guide

Description: This document describes how to get started with ESP8266_RTOS_SDK, which is the official development framework for the ESP8266EX chip.

ESP-WROOM-02 PCB Design and Module Placement Guide

Description: The ESP-WROOM-02 module is designed to be soldered to a host PCB. This document compares six different placements of the antenna on a host board and provides notes on designing PCB.

ESP8266 Hardware Resources

Description: This zip package includes manufacturing specifications of the ESP8266 board and the modules, manufacturing BOM and schematics.

ESP8266 AT Command Examples

Description: This document introduces some specific examples of using Espressif AT commands, including single connection as a TCP Client, UDP transmission and transparent transmission, and multiple connection as a TCP server.

ESP8266 AT Instruction Set

Description: This document provides lists of AT commands based on ESP8266_NONOS_SDK, including user-defined AT commands, basic AT commands, Wi-Fi AT commands and TCP/IP-related AT commands. It also introduces the downloading of AT firmware into flash.

TCP/UDP UART Passthrough Test Demonstration

Description: This guide is intended to help users run a TCP & UDP passthrough test on the ESP8266 IoT platform.

FAQ



A.2. Must-Have Resources

ESP8266 SDKs •

Description: This website page provides links to the latest version of ESP8266 SDK and the older ones.

. ESP8266 Tools

> Description: This website page provides links to the ESP8266 flash download tools and ESP8266 performance evaluation tools.

- . ESP8266 App
- ESP8266 Certification and Test Guide •
- ESP8266 BBS •
- ESP8266 Resources ٠



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